



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q78432

Hien Boon TAN , et al.

Appln. No.: 10/721,382

Group Art Unit: Not Yet Assigned

Confirmation No.: Not Yet Assigned

Examiner: Not Yet Assigned

Filed: November 26, 2003

For: HIGH DENSITY CHIP SCALE LEADFRAME PACKAGE AND METHOD OF
MANUFACTURING THE PACKAGE

PETITION UNDER 37 C.F.R. § 1.182 TO SUBMIT REPLACEMENT DRAWINGS

BOX PGPUB DRAWINGS

Commissioner for Patents

Washington, DC 20231

Sir:

Applicants' respectfully petition to have the formal drawings submitted herewith accepted for publication with the present application. Submitted herewith, please find 8 sheets for formal drawings in compliance with 37 C.F.R. § 1.184, to replace drawings originally filed with the present application on November 25, 2003. These formal drawings are being submitted within fourteen months from the earliest filing date for which a benefit is sought under title 35 U.S.C. (November 27, 2002).

A petition under Rule 1.182 is believed appropriate since this situation is not specifically provided for in the regulations.

A petition fee of \$130.00 is being submitted herewith as set for in § 1.17(h). The USPTO is directed and authorized to charge all required fees, including any fee required for the instant petition, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880.

01/28/2004 SSANDARA 00000005 10721382

130.00 DP

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Please also credit any overpayments to said Deposit Account. A duplicate copy of this paper is attached.

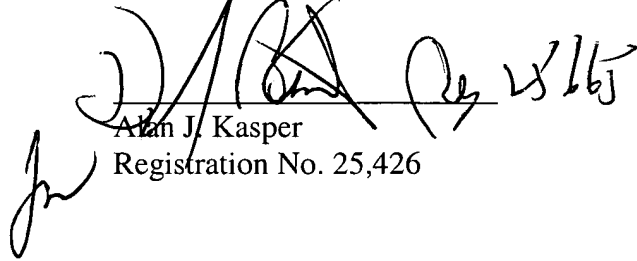
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WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Respectfully submitted,


Alan J. Kasper
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Date: January 27, 2004